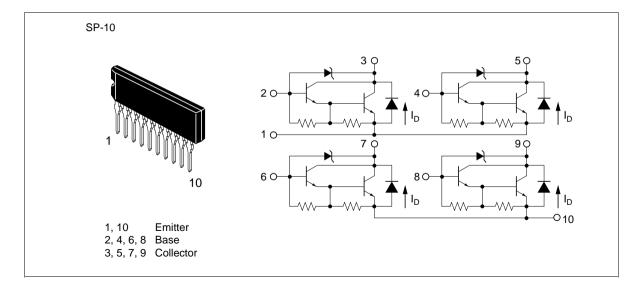
Silicon NPN Epitaxial

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Application

Low frequency power amplifier

Outline





Absolute Maximum Ratings (for each device, $Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	27	V	
Collector to emitter voltage	V _{CEO}	27	V	
Emitter to base voltage	V _{EBO}	7	V	
Collector current	Ι _c	2	А	
Collector peak current	I _{C(peak)}	4	А	
Diode current	I _D	2	А	
Collector power dissipation	P _c * ¹	4	W	
	$P_{c}^{*1} (T_{c} = 25^{\circ}C)$	28		
Junction temperature	Tj	150	٥C	
Storage temperature	Tstg	-55 to +150	°C	

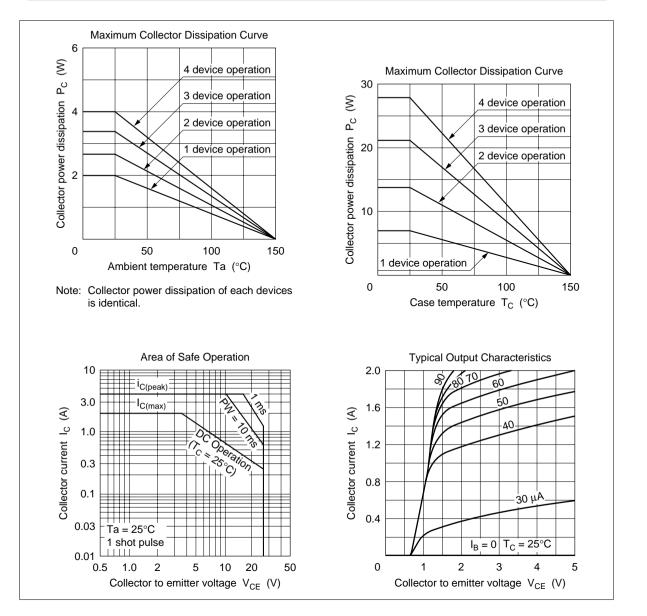
Note: 1. 4 devices operation.

Electrical Characteristics (for each device, $Ta = 25^{\circ}C$)

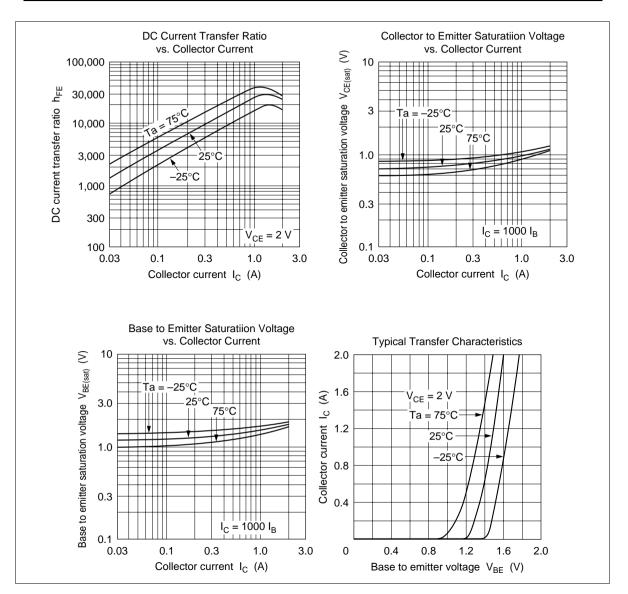
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CBO}$	27	_	—	V	$I_{c} = 1 \text{ mA}, I_{E} = 0$
Collector to emitter sustain voltage	$V_{\text{CEO}(\text{SUS})}$	28	_	36	V	I_{c} = 1 A, L = 20 mH, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	—	—	V	$I_{\rm E} = 5 {\rm mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	10	μΑ	$V_{CB} = 20 \text{ V}, \text{ I}_{E} = 0$
	I _{CEO}	—	—	10	_	V_{ce} = 20 V, R_{be} = ∞
DC current transfer ratio	h_{FE}	7000	—	30000		$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}$
	h _{FE}	2000	—	—	_	$V_{ce} = 2 V, I_c = 2 A^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	_	1.5	V	$I_{c} = 2 \text{ A}, I_{B} = 2 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)}$	—	—	2.0	V	$I_{c} = 2 \text{ A}, I_{B} = 2 \text{ mA}^{*1}$
C to E diode forward current	V _D	_	_	3.5	V	I _D = 2 A
Note: 1 Pulse test						

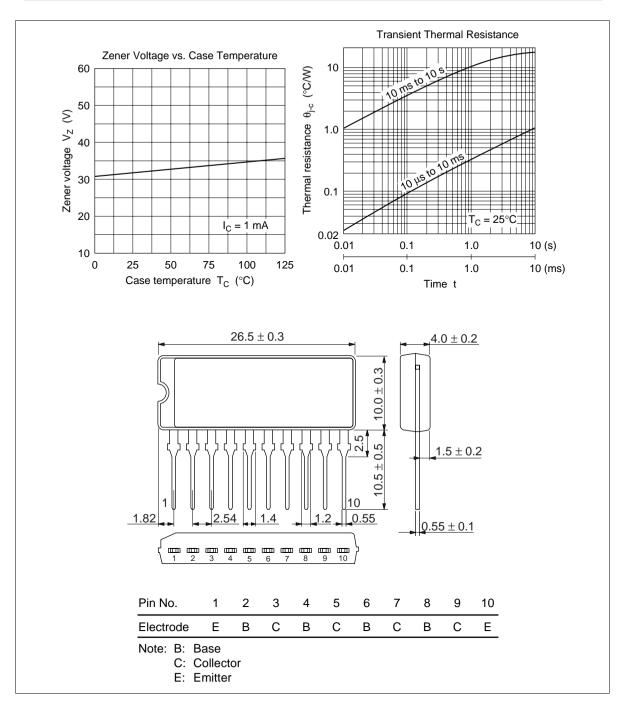
Note: 1. Pulse test.

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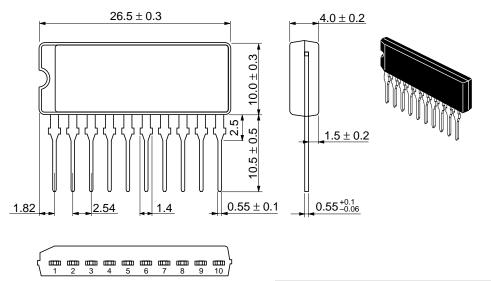
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Unit: mm



Hitachi Code	SP-10
JEDEC	—
EIAJ	—
Weight (reference value)	2.9 g

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